



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

0755-83047638

ysbdt@szyoushang.cn

www.szyoushang.cn



企业微信二维码



企业QQ二维码

Features

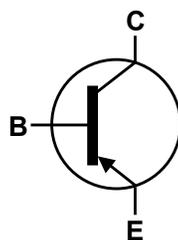
- $BV_{CEO} > -60V$
- $I_C = -1A$ High Continuous Collector Current
- $I_{CM} = -2A$ Peak Pulse Current
- $R_{sat} = 295m\Omega$ for a Low Equivalent On-Resistance
- h_{FE} characterised up to $-2A$ for High Current Gain Hold Up
- Complementary NPN Type: NK-FMMT491

Mechanical Data

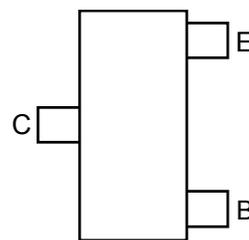
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 
- Weight 0.008 grams (Approximate)



Top View



Device Symbol



Top View
Pin-Out

Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CB0}	-80	V
Collector-Emitter Voltage	V_{CEO}	-60	V
Emitter-Base Voltage	V_{EBO}	-7	V
Continuous Collector Current	I_C	-1	A
Peak Pulse Collector Current (Single Pulse)	I_{CM}	-2	A
Base Current	I_B	-200	mA

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

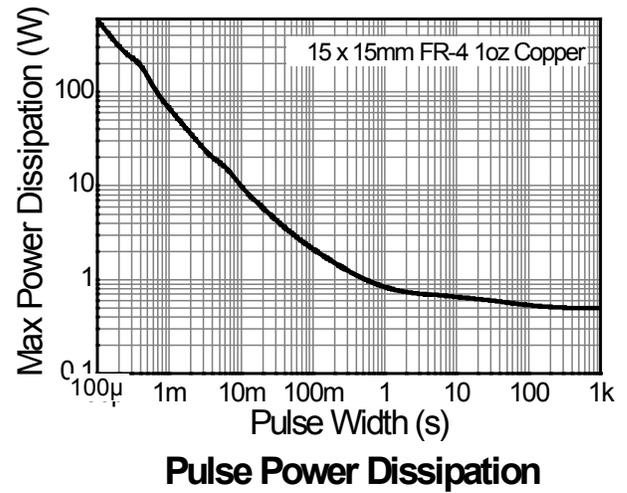
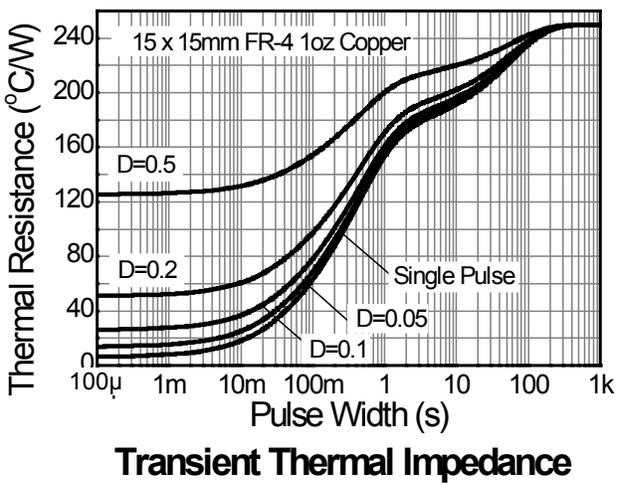
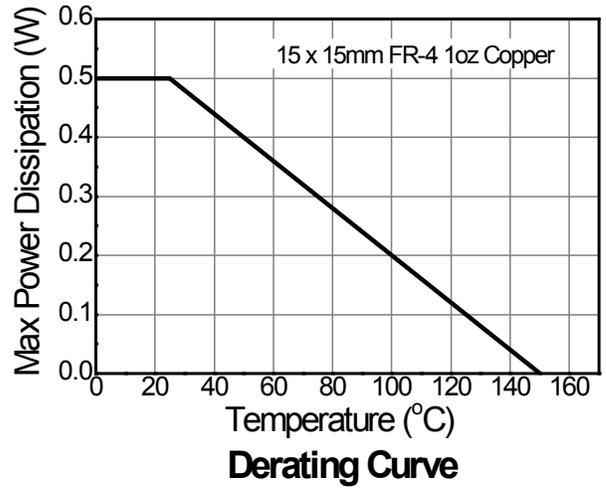
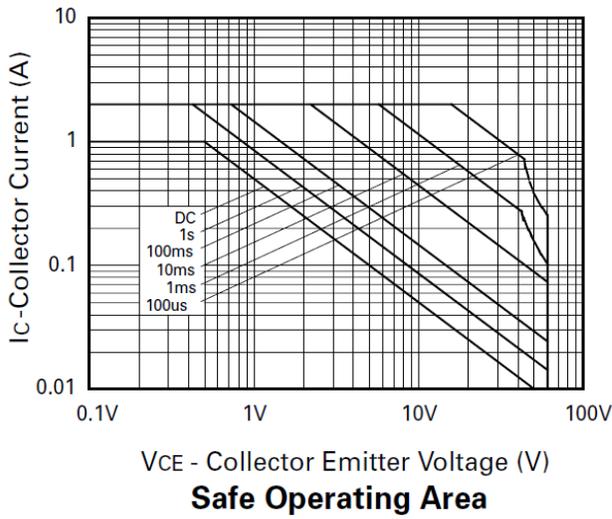
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	500	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	250	$^\circ\text{C/W}$
Thermal Resistance, Junction to Lead (Note 6)	$R_{\theta JL}$	197	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted with the collector lead on 15mm × 15mm 1oz copper that is on a single-sided FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 6. Thermal resistance from junction to solder-point (at the end of the collector lead).
 7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

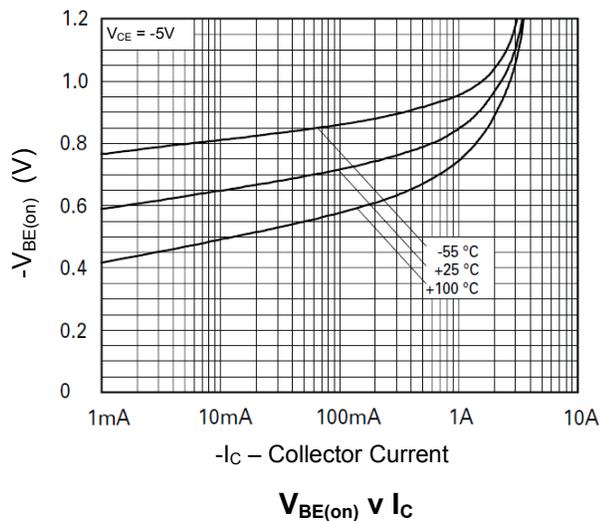
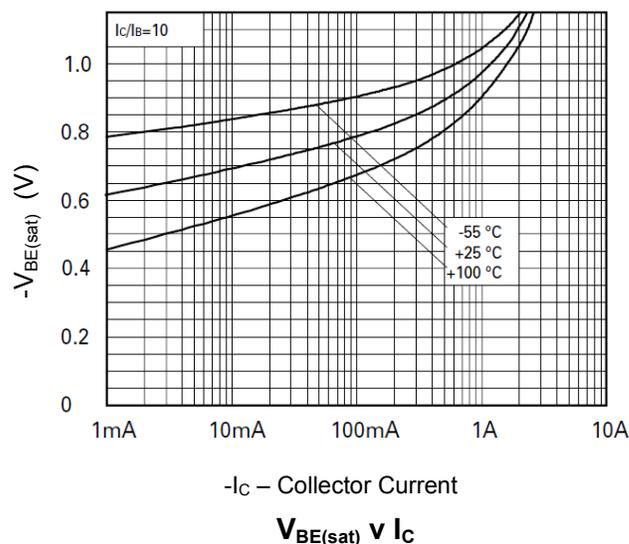
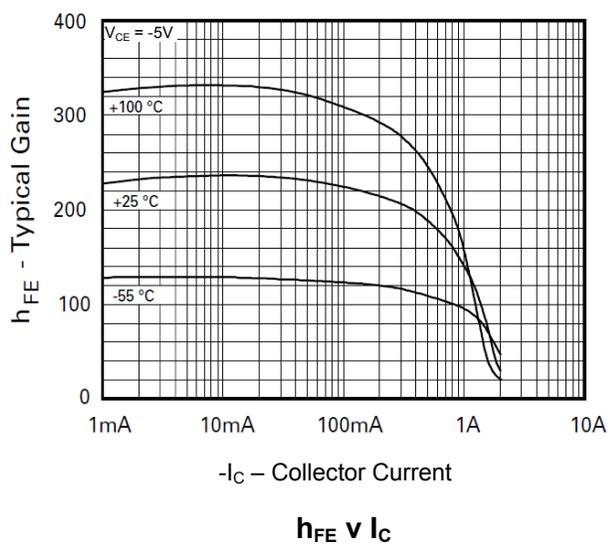
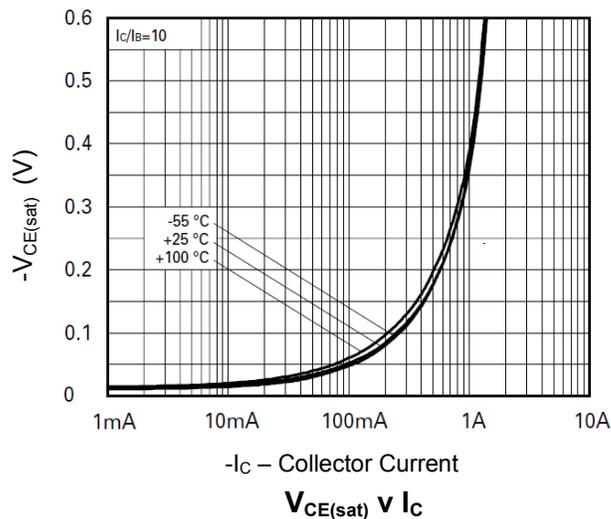
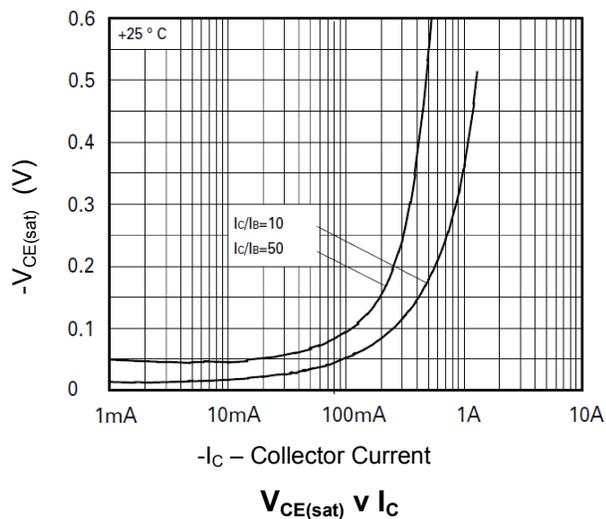


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	-80	—	—	V	$I_C = -100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 8)	BV_{CEO}	-60	—	—	V	$I_C = -10\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	-7	-8.1	—	V	$I_E = -100\mu\text{A}$
Collector-Base Cut-Off Current	I_{CBO}	—	<1	-100	nA	$V_{CB} = -60\text{V}$
Emitter-Base Cut-Off Current	I_{EBO}	—	<1	-100	nA	$V_{EB} = -5.6\text{V}$
Collector-Emitter Cut-Off Current	I_{CES}	—	<1	-100	nA	$V_{CE} = -50\text{V}$
DC Current Gain (Note 8)	h_{FE}	100 100 80 15	220 175 155 40	— 300 — —	—	$I_C = -1\text{mA}, V_{CE} = -5\text{V}$ $I_C = -500\text{mA}, V_{CE} = -5\text{V}$ $I_C = -1\text{A}, V_{CE} = -5\text{V}$ $I_C = -2\text{A}, V_{CE} = -5\text{V}$
Collector-Emitter Saturation Voltage (Note 8)	$V_{CE(sat)}$	—	-155 -295	-180 -350	mV	$I_C = -500\text{mA}, I_B = -50\text{mA}$ $I_C = -1\text{A}, I_B = -100\text{mA}$
Base-Emitter Saturation Voltage (Note 8)	$V_{BE(sat)}$	—	-965	-1200	mV	$I_C = -1\text{A}, I_B = -100\text{mA}$
Base-Emitter Turn-On Voltage (Note 8)	$V_{BE(on)}$	—	-830	-1000	mV	$I_C = -1\text{A}, V_{CE} = -5\text{V}$
Transition frequency	f_T	150	—	—	MHz	$V_{CE} = -10\text{V}, I_C = -50\text{mA},$ $f = 100\text{MHz}$
Output Capacitance	C_{obo}	—	—	10	pF	$V_{CB} = -10\text{V}, f = 1\text{MHz}$

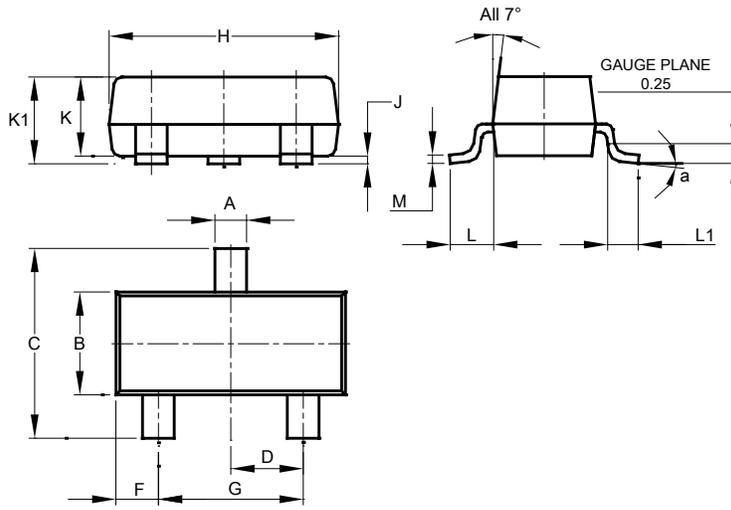
 Note: 8. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

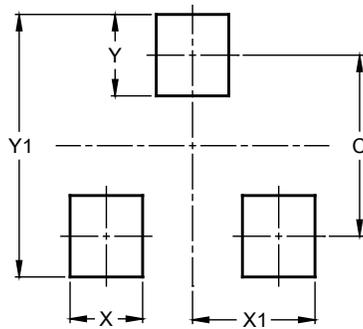
SOT23



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

SOT23



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9